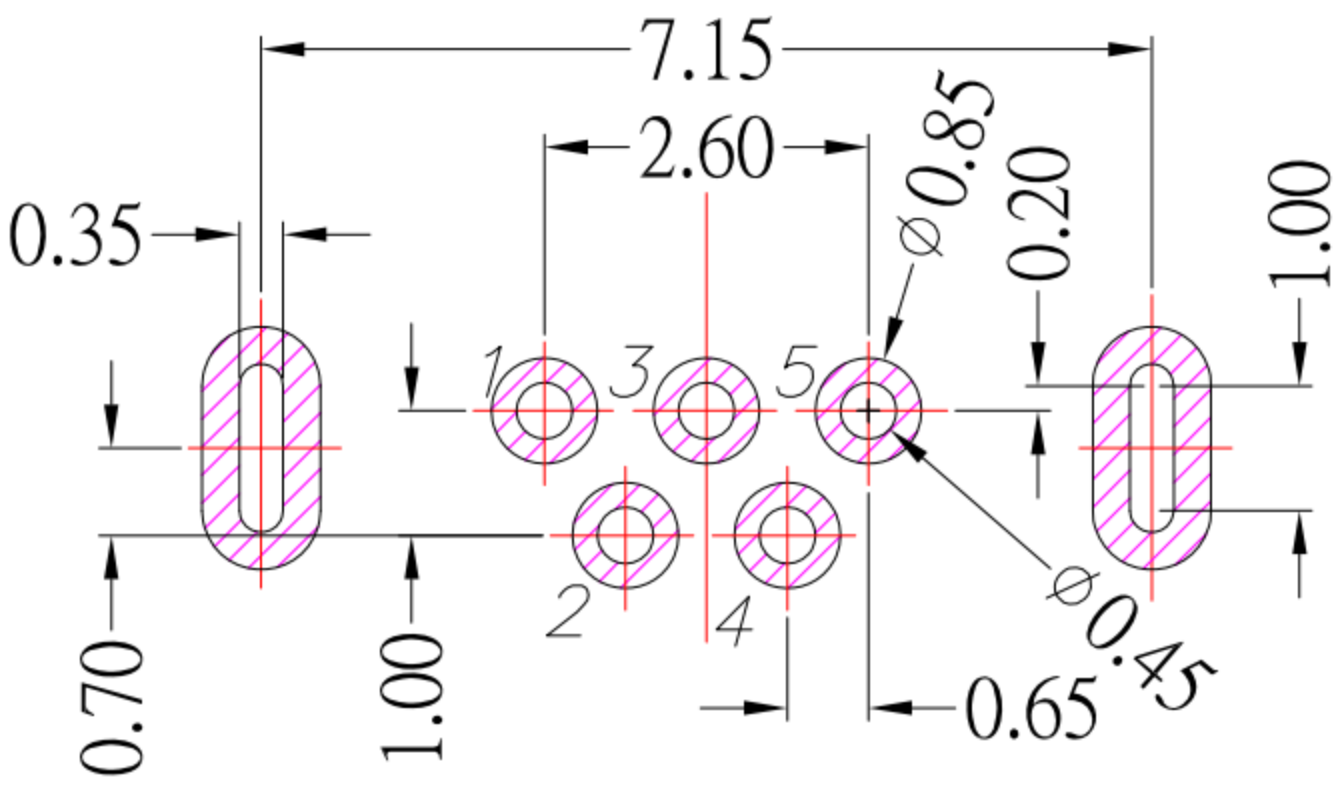




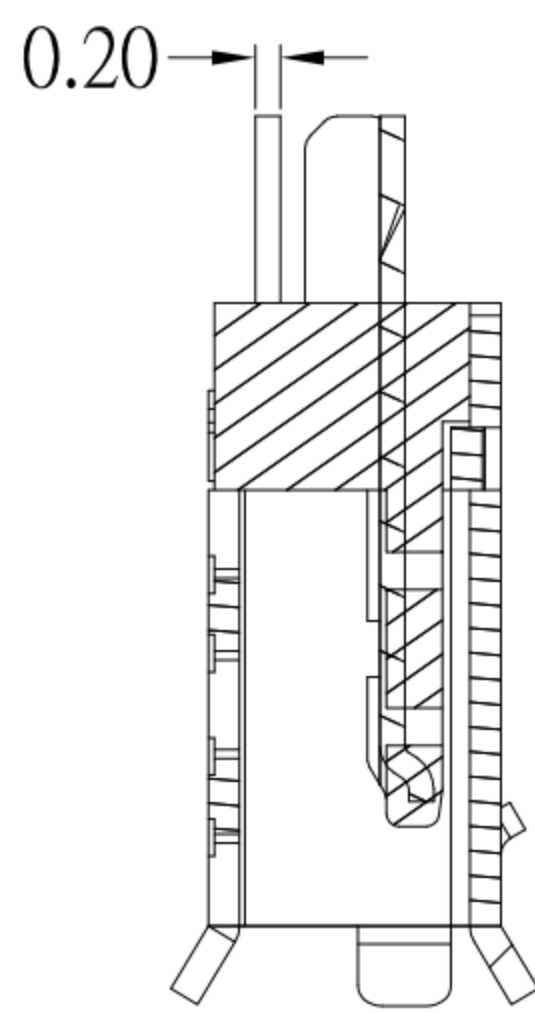
MRUSB-5AB-V-x-S347

鍍層厚度：

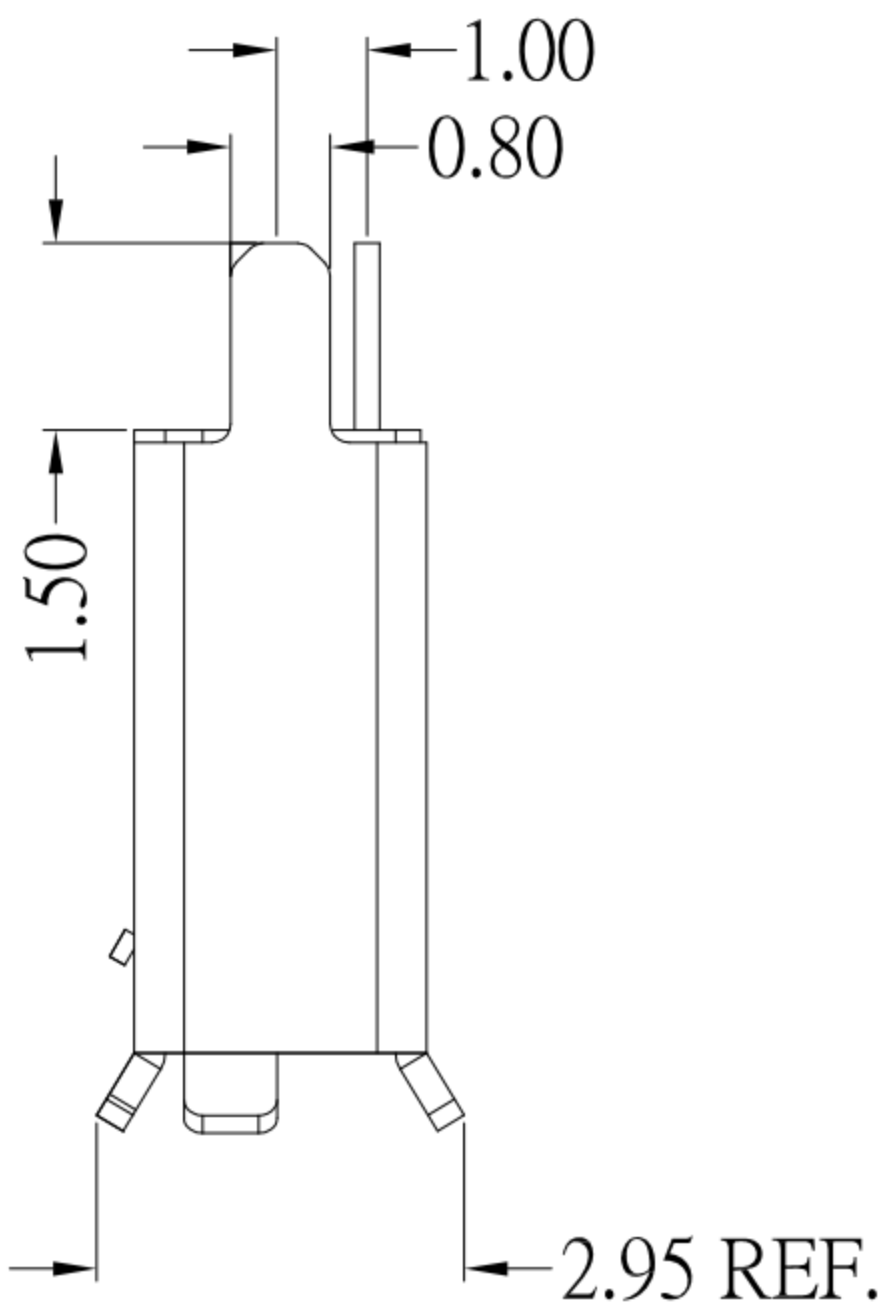
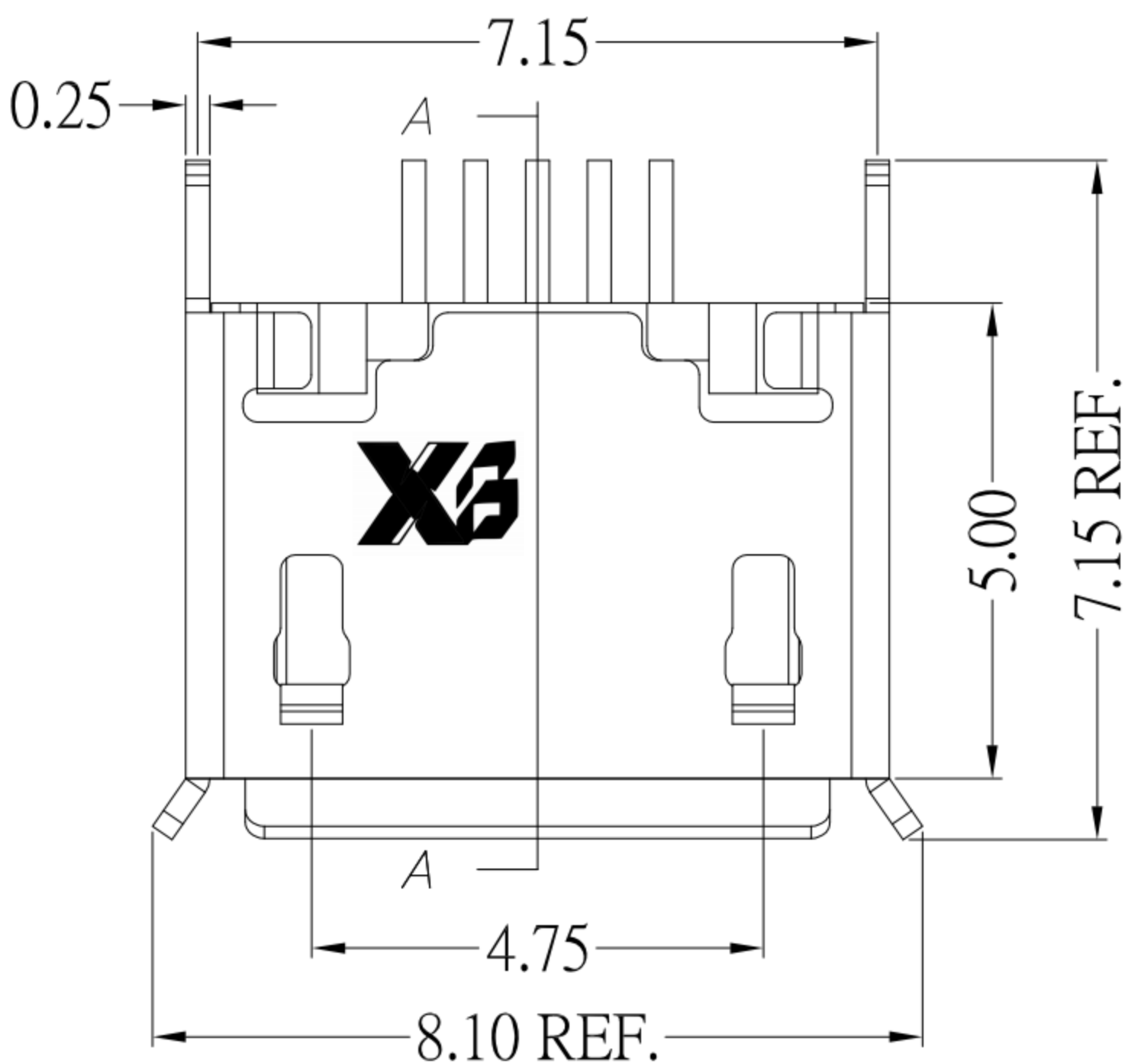
Blank : 1u"
2 : 15u"
3 : 30u"



P.C.B LAYOUT MOUNTING PATTERN



SECTION A-A



NOTES:

MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: PHOSPHOR BRONZE
- 1.3 Shell: SUS

Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overal
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.8A(PIN 1&5) MAX ; 1.0A(PIN 2&3&4) MAX
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C



TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 Above 5 ~ 15 Above 15 ~ 30 Above 30 ~ 50 Angle	±0.2 ±0.3 ±0.4 ±0.5 ±0.3°	3RD. ANGEL'S		UNITS	MM
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2	新增尺寸	Jack	010622
1	更新圖面	Jack	111621
ITEM NO.	DESCRIPTION	DRAWN	DATE

DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR
Jack Lu	01/06/22	FINISH		MODLE	MICRO USB 5PF ABTYPE 直立式 捲邊 腳長 1.5mm
CHECKED BY:	DATE	SCALE	1 : 1	DWG NO.	MRUSB-5AB-V-x-S347
Jacky Chen	01/06/22	SHEET NO.	1 of 1	PART NO.	MRUSB-5AB-V-x-S347
APPROVED BY:	DATE				
Tony Kao	01/06/22				